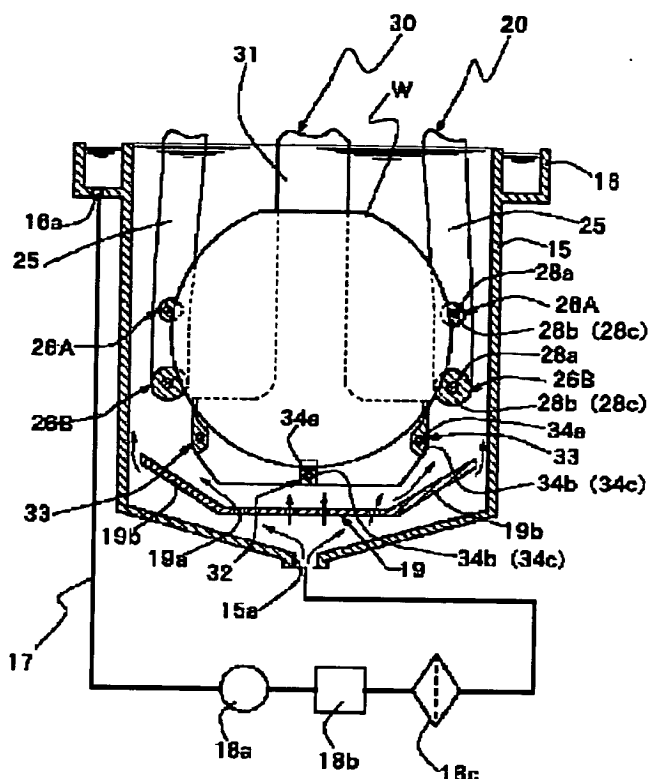


Patent Abstracts of Japan

TITLE : TREATMENT APPARATUS



CONSTITUTION: This is a treatment apparatus which includes a treatment tank 15 for containing a treatment solution in which a semiconductor wafer W is dipped, a wafer chuck 20 for holding and conveying the semiconductor wafer W to the treatment tank 15, and a wafer boat 30 for holding the semiconductor wafer W in the state where the semiconductor wafer W is dipped in the treatment solution in the treatment tank 15. Each of at least a semiconductor wafer W holder of the wafer chuck 20 and a semiconductor wafer W holder of the wafer boat 30 is formed with resilient stainless steel core materials 28a, 34a and synthetic resin cover layers 28b, 28c, 34b, 34c which cover outer surfaces of the core materials 28a, 34a and which have chemical resistance against the treatment solutions of different kinds. In this case, for the synthetic resin cover layer there is used any one of polytetrafluoroethylene, tetrafluoroethylene-perfluoroalkylvinyl ether copolymer or polyvinylidene fluoride.

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